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# Global SiC Wafer Thinning Equipment Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

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## Abstracts

According to our (Global Info Research) latest study, the global SiC Wafer Thinning Equipment market size was valued at US$ 117 million in 2024 and is forecast to a readjusted size of USD 341 million by 2031 with a CAGR of 16.7% during review period.

Wafer Grinder uses a centrally located robot to move a wafer from an input station to a measuring station. Thereafter, the wafer is moved into a grind station and a wash station sequentially. The robot is able to move a wafer from the wash station to either the measuring station for after-grinding measurements or directly to an output station. During grinding of one wafer, a second wafer may be held between the measuring station and the grind station while a ground wafer is moved from the wash station to the measuring station for after-grinding measurements.

This report only studies Silicon Carbide Wafer Thinning Equipment.

The global SiC Wafer Thinning Equipment market is witnessing significant growth, driven by the increasing demand for semiconductors in various industries such as consumer electronics, automotive, and telecommunications. The Asia-Pacific region remains the largest consumer market, accounting for over 60% of the global market share. This trend is expected to continue due to the region's strong semiconductor industry, technological advancements, and growing demand for energy-efficient power devices.

The global key manufacturers of SiC Wafer Thinning Equipment include Disco, TSD, etc. In 2023, the global top five players had a share approximately 81% in terms of revenue.

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Among different types of SiC wafer thinning equipment, fully automated systems dominate the market, capturing approximately 77% of the total share in 2024. This reflects the industry's growing demand for precision, scalability, and high-efficiency production processes. Fully automated equipment provides improved throughput and minimizes the risk of human error, making it the preferred choice for manufacturers aiming to scale their operations and ensure high-quality output.

Interms of applications, wafers sized 6 inches and below are the primary demand drivers. These smaller wafers make up approximately 70% of the market in 2024. The widespread use of smaller wafers in power electronics and semiconductor devices, particularly in electric vehicles and renewable energy applications, supports this demand. As SiC continues to gain traction in the power semiconductor sector, the demand for wafer thinning equipment for smaller wafer sizes is expected to increase.

Market Driving Factors

Expansion of the Electric Vehicle (EV) Market: SiC materials are particularly suitable for use in power modules for electric vehicles (EVs) due to their superior thermal conductivity and high voltage tolerance. With the rapid growth of the electric vehicle market, the demand for SiC wafers is increasing, which in turn drives the demand for wafer thinning equipment.

Advances in Energy Conversion and Storage Technologies: In high-efficiency energy conversion and storage fields, such as solar inverters and battery management systems, the use of SiC materials can significantly improve efficiency. The market's demand for high-performance components has driven the production and thinning of SiC wafers.

Demand for 5G and High-Frequency Electronics: The demand for SiC materials is rising in 5G networks and other high-frequency electronic devices due to SiC's excellent performance in high-frequency and high-power applications. This has led to an increase in the demand for SiC wafer production and processing equipment.

Market Restraints

Process Complexity: The wafer thinning process for SiC wafers involves high-precision techniques and is technically challenging. The instability of the process may lead to quality issues, affecting market confidence.

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Intensifying Competition: As the SiC market rapidly develops, more companies are entering the field, and market competition is becoming increasingly intense. This may lead to price wars and margin compression.

Technological Iteration: With the fast pace of technological updates, the introduction of new technologies and equipment may quickly render existing equipment obsolete. Companies need to continue investing in research and development to maintain competitiveness.

This report is a detailed and comprehensive analysis for global SiC Wafer Thinning Equipment market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global SiC Wafer Thinning Equipment market size and forecasts, in consumption value ($ Million), sales quantity (Units), and average selling prices (US$/Unit), 2020-2031

Global SiC Wafer Thinning Equipment market size and forecasts by region and country, in consumption value ($ Million), sales quantity (Units), and average selling prices (US$/Unit), 2020-2031

Global SiC Wafer Thinning Equipment market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (Units), and average selling prices (US$/Unit), 2020-2031

Global SiC Wafer Thinning Equipment market shares of main players, shipments in revenue ($ Million), sales quantity (Units), and ASP (US$/Unit), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for SiC Wafer Thinning Equipment

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To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global SiC Wafer Thinning Equipment market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Disco, TSD, TOKYO SEIMITSU, Engis Corporation, Okamoto Semiconductor Equipment Division, Revasum, Koyo Machinery, G&N, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

SiC Wafer Thinning Equipment market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Full-Automatic

Semi-Automatic

Market segment by Application

6 Inch and Below

8 Inch and Above

Major players covered

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Disco

TSD

TOKYO SEIMITSU

Engis Corporation

Okamoto Semiconductor Equipment Division

Revasum

Koyo Machinery

G&N

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe SiC Wafer Thinning Equipment product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of SiC Wafer Thinning Equipment, with price, sales quantity, revenue, and global market share of SiC Wafer Thinning Equipment from 2020 to 2025.

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Chapter 3, the SiC Wafer Thinning Equipment competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the SiC Wafer Thinning Equipment breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2020 to 2031.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2020 to 2031.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2020 to 2025.and SiC Wafer Thinning Equipment market forecast, by regions, by Type, and by Application, with sales and revenue, from 2026 to 2031.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of SiC Wafer Thinning Equipment.

Chapter 14 and 15, to describe SiC Wafer Thinning Equipment sales channel, distributors, customers, research findings and conclusion.

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